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Understanding Embedded - FPGAs (Field Programmable Gate Array)

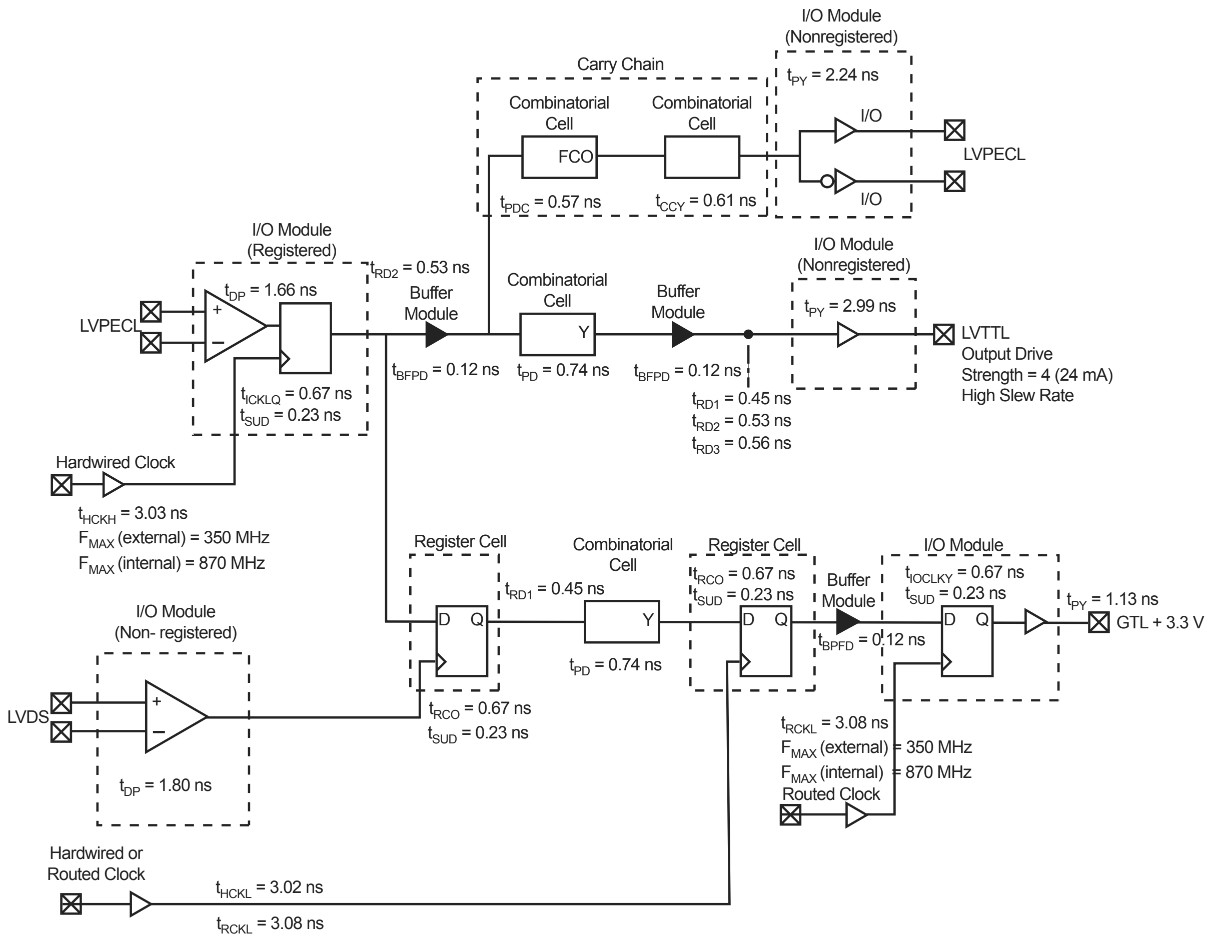
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	198
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	352-BFCQFP with Tie Bar
Supplier Device Package	352-CQFP (75x75)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax500-cq352m

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{HCKL}$

$= (1.72 + 0.53 + 0.23) - 3.02 = -0.54$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.02 + 0.67 + 0.45 + 2.99 = 7.13$ ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{RCKH}$

$= (1.72 + 0.53 + 0.23) - 3.13 = -0.65$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.13 + 0.67 + 0.45 + 3.03 = 7.24$ ns

5 V Tolerance

There are two schemes to achieve 5 V tolerance:

1. 3.3 V PCI and 3.3 V PCI-X are the only I/O standards that directly allow 5 V tolerance. To implement this, an internal clamp diode between the input pad and the VCCI pad is enabled so that the voltage at the input pin is clamped, as shown in EQ 3:

Vinput = VCCI + Vdiode = 3.3 V + 0.7 V = 4.0 V

EQ 3

The internal VCCI clamp diode is only enabled while the device is powered on, so the voltage at the input will not be clamped if the VCCI or VCCA are powered off. An external series resistor (~100 Ω) is required between the input pin and the 5 V signal source to limit the current to less than 20 mA (Figure 2-3). The 100 Ω resistor was chosen to meet the input Tr/Tf requirement (Table 2-19 on page 2-21). The GND clamp diode is available for all I/O standards and always enabled.

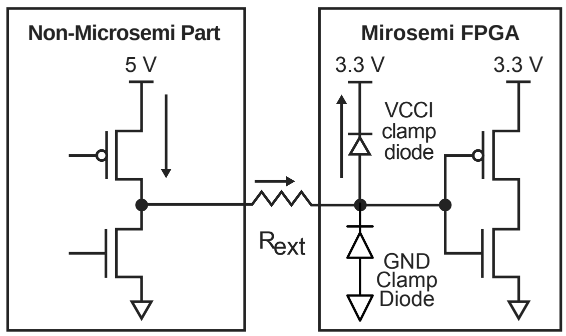


Figure 2-3 • **Use of an External Resistor for 5 V Tolerance**

2. 5 V tolerance can also be achieved with 3.3 V I/O standards (3.3 V PCI, 3.3 V PCI-X, and LVTTL) using a bus-switch product (e.g. IDTQS32X2384). This will convert the 5 V signal to a 3.3 V signal with minimum delay (Figure 2-4).

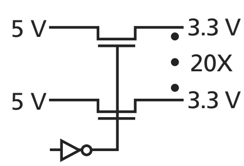


Figure 2-4 • **Bus Switch IDTQS32X2384**

Simultaneous Switching Outputs (SSO)

When multiple output drivers switch simultaneously, they induce a voltage drop in the chip/package power distribution. This simultaneous switching momentarily raises the ground voltage within the device relative to the system ground. This apparent shift in the ground potential to a non-zero value is known as simultaneous switching noise (SSN) or more commonly, ground bounce.

SSN becomes more of an issue in high pin count packages and when using high performance devices such as the Axcelerator family. Based upon testing, Microsemi recommends that users not exceed eight simultaneous switching outputs (SSO) per each VCCI/GND pair. To ease this potential burden on designers, Microsemi has designed all of the Axcelerator BGAs[3] to not exceed this limit with the exception of the CS180, which has an I/O to VCCI/GND pair ratio of nine to one.

Please refer to the *Simultaneous Switching Noise and Signal Integrity* application note for more information.

3. *The user should note that in Bank 8 of both AX1000-FG484 and AX500-FG484, there are local violations of this 8:1 ratio.*

Using the Differential I/O Standards

Differential I/O macros should be instantiated in the netlist. The settings for these I/O standards cannot be changed inside Designer. Note that there are no tristated or bidirectional I/O buffers for differential standards.

Using the Voltage-Referenced I/O Standards

Using these I/O standards is similar to that of single-ended I/O standards. Their settings can be changed in Designer.

Using DDR (Double Data Rate)

In Double Data Rate mode, new data is present on every transition of the clock signal. Clock and data lines have identical bandwidth and signal integrity requirements, making it very efficient for implementing very high-speed systems.

To implement a DDR, users need to:

1. Instantiate an input buffer (with the required I/O standard)
2. Instantiate the DDR_REG macro (Figure 2-6)
3. Connect the output from the Input buffer to the input of the DDR macro

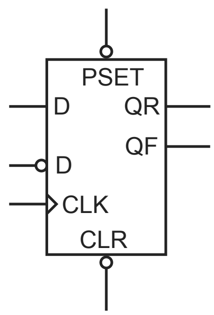


Figure 2-6 • **DDR Register**

Macros for Specific I/O Standards

There are different macro types for any I/O standard or feature that determine the required VCCI and VREF voltages for an I/O. The generic buffer macros require the LVTTL standard with slow slew rate and 24 mA-drive strength. LVTTL can support high slew rate but this should only be used for critical signals.

Most of the macro symbols represent variations of the six generic symbol types:

- CLKBUF: Clock Buffer
- HCLKBUF: Hardwired Clock Buffer
- INBUF: Input Buffer
- OUTBUF: Output Buffer
- TRIBUF: Tristate Buffer
- BIBUF: Bidirectional Buffer

Other macros include the following:

- Differential I/O standard macros: The LVDS and LVPECL macros either have a pair of differential inputs (e.g. INBUF_LVDS) or a pair of differential outputs (e.g. OUTBUF_LVPECL).
- Pull-up and pull-down variations of the INBUF, BIBUF, and TRIBUF macros. These are available only with TTL and LVCMOS thresholds. They can be used to model the behavior of the pull-up and pull-down resistors available in the architecture. Whenever an input pin is left unconnected, the output pin will either go high or low rather than unknown. This allows users to leave inputs unconnected without having the negative effect on simulation of propagating unknowns.
- DDR_REG macro. It can be connected to any I/O standard input buffers (i.e. INBUF) to implement a double data rate register. Designer software will map it to the I/O module in the same way it maps the other registers to the I/O module.

2.5 V LVCMOS

Low-Voltage Complementary Metal-Oxide Semiconductor for 2.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 2.5 V applications. It uses a 3.3 V tolerant CMOS input buffer and a push-pull output buffer.

Table 2-23 **• DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
-0.3	0.7	1.7	3.6	0.4	2.0	12	–12

AC Loadings

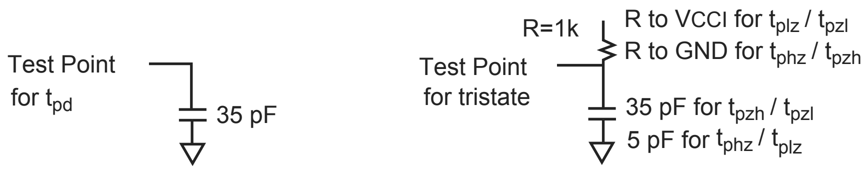


Figure 2-16 **• AC Test Loads**

Table 2-24 **• AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
0	2.5	1.25	N/A	35

*Note: * Measuring Point = VTRIP*

Timing Characteristics

Table 2-28 **• 1.8V LVCMOS I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.7 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS18 Output Module Timing								
t_{DP}	Input Buffer		3.26		3.71		4.37	ns
t_{PY}	Output Buffer		4.55		5.18		6.09	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.82		2.83		2.84	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		3.43		3.45		3.46	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.01		6.85		8.05	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.73		7.67		9.01	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

SSTL2

Stub Series Terminated Logic for 2.5 V is a general-purpose 2.5 V memory bus standard (JESD8-9). The Axcelerator devices support both classes of this standard. This requires a differential amplifier input buffer and a push-pull output buffer.

Class I

Table 2-44 **• DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
–0.3	VREF – 0.2	VREF + 0.2	3.6	VREF – 0.57	VREF + 0.57	7.6	–7.6

AC Loadings

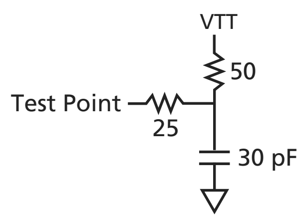


Figure 2-21 **• AC Test Loads**

Table 2-45 **• AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 0.75	VREF + 0.75	VREF	1.25	30

*Note: * Measuring Point = VTRIP*

Timing Characteristics

Table 2-46 **• 2.5 V SSTL2 Class I I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
2.5 V SSTL2 Class I I/O Module Timing								
t_{DP}	Input Buffer		1.83		2.08		2.45	ns
t_{PY}	Output Buffer		2.39		2.72		3.20	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

single-ended, or voltage-referenced standard. The [H]CLKxN pad can only be used as a differential pair with [H]CLKxP.

The block marked “/i Delay Match” is a fixed delay equal to that of the i divider. The “/j Delay Match” block has the same function as its j divider counterpart.

Functional Description

Figure 2-48 on page 2-75 illustrates a block diagram of the PLL. The PLL contains two dividers, i and j, that allow frequency scaling of the clock signal:

- The i divider in the feedback path allows multiplication of the input clock by integer factors ranging from 1 to 64, and the resultant frequency is available at the output of the PLL block.
- The j divider divides the PLL output by integer factors ranging from 1 to 64, and the divided clock is available at CLK1.
- The two dividers together can implement any combination of multiplication and division up to a maximum frequency of 1 GHz on CLK1. Both the CLK1 and CLK2 outputs have a fixed 50/50 duty cycle.
- The output frequencies of the two clocks are given by the following formulas (f_{REF} is the reference clock frequency):

$$f_{CLK1} = f_{REF} * (\text{DividerI}) / (\text{DividerJ})$$

EQ 4

$$f_{CLK2} = f_{REF} * (\text{DividerI})$$

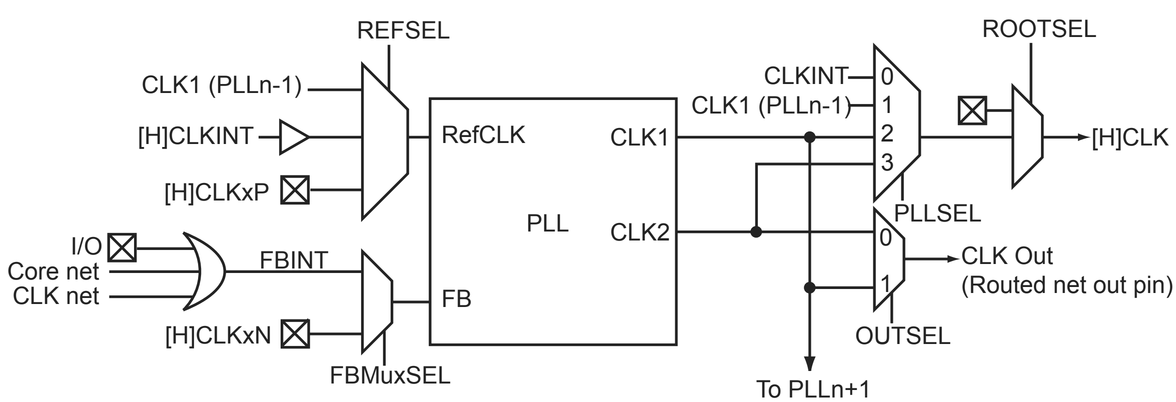
EQ 5

- CLK2 provides the PLL output directly—without division

The input and output frequency ranges are selected by LowFreq and Osc(2:0), respectively. These functions and their possible values are detailed in Table 2-80 on page 2-77.

The delay lines shown in Figure 2-48 on page 2-75 are programmable. The feedback clock path can be delayed (using the five DelayLine bits) relative to the reference clock (or vice versa) by up to 3.75 ns in increments of 250 ps. Table 2-80 on page 2-77 describes the usage of these bits. The delay increments are independent of frequency, so this results in phase changes that vary with frequency. The delay value is highly dependent on V_{CC} and the speed grade.

Figure 2-49 is a logical diagram of the various control signals to the PLL and shows how the PLL interfaces with the global and routing networks of the FPGA. Note that not all signals are user-accessible. These non-user-accessible signals are used by the place-and-route tool to control the configuration of the PLL. The user gains access to these control signals either based upon the connections built in the user's design or through the special macros (Table 2-84 on page 2-81) inserted into the design. For example, connecting the macro PLLOUT to CLK2 will control the OUTSEL signal.



Note: Not all signals are available to the user.

Figure 2-49 **• PLL Logical Interface**

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

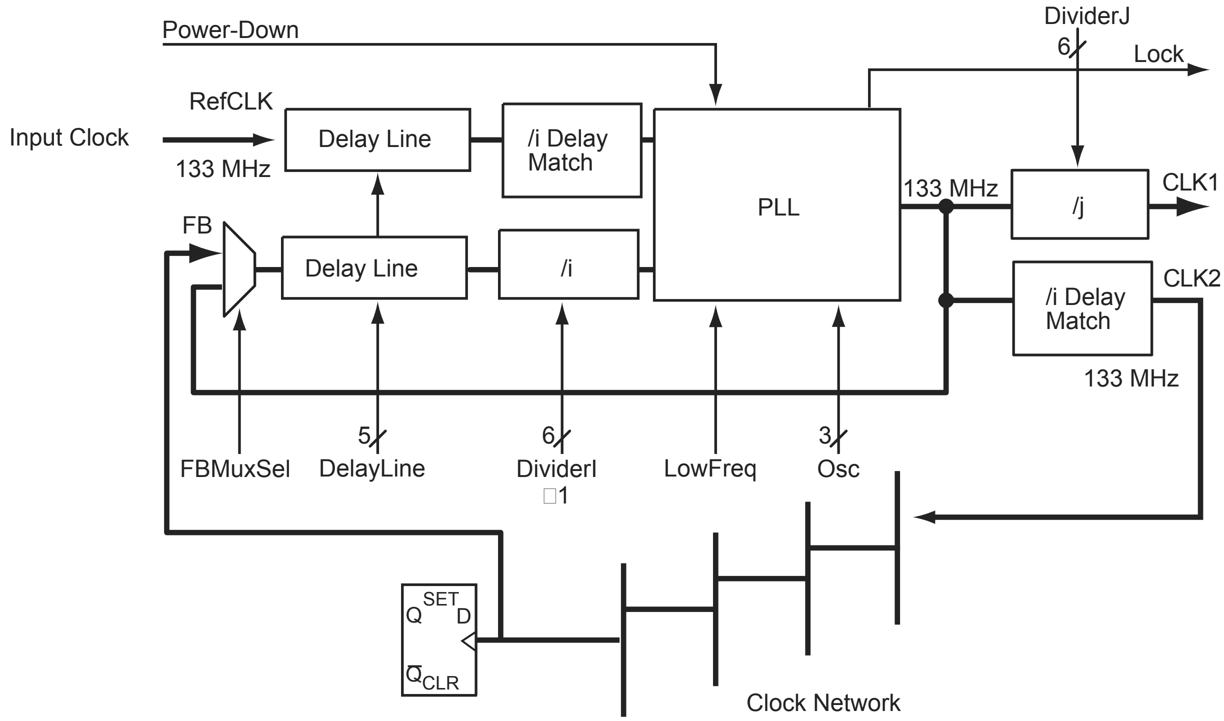


Figure 2-56 **• Using the PLL for Clock Deskewing**

***Table 2-99* • Two FIFO Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		13.75		15.66		18.41	ns
t_{WHD}	Write Hold		0.00		0.00		0.00	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		1.76		1.76		1.76	ns
t_{WCKP}	Minimum WCLK Period	2.51		2.51		2.51		ns
t_{RSU}	Read Setup		14.33		16.32		19.19	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.73		0.73		0.73	ns
t_{RCKL}	RCLK Low		1.89		1.89		1.89	ns
t_{RCKP}	Minimum RCLK period	2.62		2.62		2.62		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Nonpipelined)		2.26		2.58		3.03	ns

Note: Timing data for these two cascaded FIFO blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

BG729	
AX1000 Function	**Pin Number**
Bank 0	
IO00NB0F0	E6
IO00PB0F0	F6
IO01NB0F0	G8
IO01PB0F0	G7
IO02NB0F0	D7
IO02PB0F0	E7
IO03NB0F0	D5
IO03PB0F0	E5
IO04NB0F0	G9
IO04PB0F0	H9
IO05NB0F0	E8
IO05PB0F0	F8
IO06NB0F0	C6
IO06PB0F0	D6
IO07NB0F0	B5
IO07PB0F0	C5
IO08NB0F0	A6
IO08PB0F0	A5
IO09NB0F0	E9
IO09PB0F0	F9
IO10NB0F0	G10
IO10PB0F0	H10
IO11NB0F0	B7
IO11PB0F0	B6
IO12NB0F1	C8
IO12PB0F1	C7
IO13NB0F1	E10
IO13PB0F1	F10
IO14NB0F1	G11
IO14PB0F1	H11
IO15NB0F1	D9
IO15PB0F1	D8
IO16NB0F1	A8
IO16PB0F1	A7
IO17NB0F1	B9
IO17PB0F1	B8

BG729	
AX1000 Function	**Pin Number**
IO18NB0F1	C10
IO18PB0F1	C9
IO19NB0F1	E11
IO19PB0F1	F11
IO20NB0F1	G12
IO20PB0F1	H12
IO21NB0F1	D11
IO21PB0F1	D10
IO22NB0F2	A10
IO22PB0F2	A9
IO23NB0F2	B11
IO23PB0F2	B10
IO24NB0F2	G13
IO24PB0F2	H13
IO25NB0F2	C12
IO25PB0F2	C11
IO26NB0F2	E12
IO26PB0F2	D12
IO27NB0F2	E13
IO27PB0F2	F13
IO28NB0F2	G14
IO28PB0F2	H14
IO29NB0F2	A12
IO29PB0F2	B12
IO30NB0F2/HCLKAN	C13
IO30PB0F2/HCLKAP	D13
IO31NB0F2/HCLKBN	F14
IO31PB0F2/HCLKBP	E14
Bank 1	
IO32NB1F3/HCLKCN	C14
IO32PB1F3/HCLKCP	B14
IO33NB1F3/HCLKDN	D16
IO33PB1F3/HCLKDP	D15
IO34NB1F3	B16
IO34PB1F3	A16
IO35NB1F3	E15
IO35PB1F3	F15

BG729	
AX1000 Function	**Pin Number**
IO36NB1F3	H15
IO36PB1F3	G15
IO37NB1F3	C17
IO37PB1F3	C16
IO38NB1F3	B18
IO38PB1F3	B17
IO39NB1F3	A18
IO39PB1F3	A17
IO40NB1F3	H16
IO40PB1F3	G16
IO41NB1F4	B19
IO41PB1F4	A19
IO42NB1F4	C19
IO42PB1F4	C18
IO43NB1F4	D18
IO43PB1F4	D17
IO44NB1F4	H17
IO44PB1F4	G17
IO45NB1F4	F17
IO45PB1F4	E17
IO46NB1F4	B20
IO46PB1F4	A20
IO47NB1F4	C21
IO47PB1F4	C20
IO48NB1F4	H18
IO48PB1F4	G18
IO49NB1F4	F18
IO49PB1F4	E18
IO50NB1F4	D20
IO50PB1F4	D19
IO51NB1F4	A22
IO51PB1F4	A21
IO52NB1F4	B22
IO52PB1F4	B21
IO53NB1F4	F19
IO53PB1F4	E19
IO54NB1F5	F20

FG484	
AX500 Function	Pin Number
VCCA	P11
VCCA	P12
VCCA	P13
VCCA	T6
VCCA	U17
VCCPLA	F10
VCCPLB	G9
VCCPLC	D13
VCCPLD	G13
VCCPLE	U13
VCCPLF	T14
VCCPLG	W10
VCCPLH	T10
VCCDA	D14
VCCDA	D5
VCCDA	F16
VCCDA	G12
VCCDA	L4
VCCDA	M18
VCCDA	T11
VCCDA	T17
VCCDA	U7
VCCDA	V14
VCCDA	V8
VCCIB0	A3
VCCIB0	B3
VCCIB0	H10
VCCIB0	H11
VCCIB0	H9
VCCIB1	A20
VCCIB1	B20
VCCIB1	H12
VCCIB1	H13
VCCIB1	H14
VCCIB2	C21

FG484	
AX500 Function	Pin Number
VCCIB2	C22
VCCIB2	J15
VCCIB2	K15
VCCIB2	L15
VCCIB3	M15
VCCIB3	N15
VCCIB3	P15
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA20
VCCIB4	AB20
VCCIB4	R12
VCCIB4	R13
VCCIB4	R14
VCCIB5	AA3
VCCIB5	AB3
VCCIB5	R10
VCCIB5	R11
VCCIB5	R9
VCCIB6	M8
VCCIB6	N8
VCCIB6	P8
VCCIB6	Y1
VCCIB6	Y2
VCCIB7	C1
VCCIB7	C2
VCCIB7	J8
VCCIB7	K8
VCCIB7	L8
VCOMPLA	D10
VCOMPLB	G10
VCOMPLC	E12
VCOMPLD	G14
VCOMPLE	W13
VCOMPLF	T13

FG484	
AX500 Function	Pin Number
VCOMPLG	V11
VCOMPLH	T9
VPUMP	D17

FG1152	
AX2000 Function	Pin Number
IO311NB7F29	N3
IO311PB7F29	P3
IO312NB7F29	P7
IO312PB7F29	R7
IO313NB7F29	P6
IO313PB7F29	R6
IO314NB7F29	M2
IO314PB7F29	N2
IO315NB7F29	N4
IO315PB7F29	P4
IO316NB7F29	R9
IO316PB7F29	R8
IO317NB7F29	N5
IO317PB7F29	P5
IO318NB7F29	R10
IO318PB7F29	R11
IO319NB7F29	L2
IO319PB7F29	L1
IO320NB7F29	N8
IO320PB7F29	P8
IO321NB7F30	M6
IO321PB7F30	N6
IO322NB7F30	P10
IO322PB7F30	P9
IO323NB7F30	L3
IO323PB7F30	M3
IO324NB7F30	M7
IO324PB7F30	N7
IO325NB7F30	K2
IO325PB7F30	K1
IO326NB7F30	G2
IO326PB7F30	H2
IO327NB7F30	L6
IO327PB7F30	L5
IO328NB7F30	N10

FG1152	
AX2000 Function	Pin Number
IO328PB7F30	N9
IO329NB7F30	J4
IO329PB7F30	K4
IO330NB7F30	J5
IO330PB7F30	K5
IO331NB7F30	M10
IO331PB7F30	M9
IO332NB7F31	L8
IO332PB7F31	M8
IO333NB7F31	F2
IO333PB7F31	F1
IO334NB7F31	J6
IO334PB7F31	K6
IO335NB7F31	H4
IO335PB7F31	H3
IO336NB7F31	K7
IO336PB7F31	L7
IO337NB7F31	G4
IO337PB7F31	G3
IO338NB7F31	K9
IO338PB7F31	L9
IO339NB7F31	H6
IO339PB7F31	H5
IO340NB7F31	H7
IO340PB7F31	J7
IO341NB7F31	J8
IO341PB7F31	K8
Dedicated I/O	
GND	A13
GND	A2
GND	A22
GND	A27
GND	A3
GND	A31
GND	A32

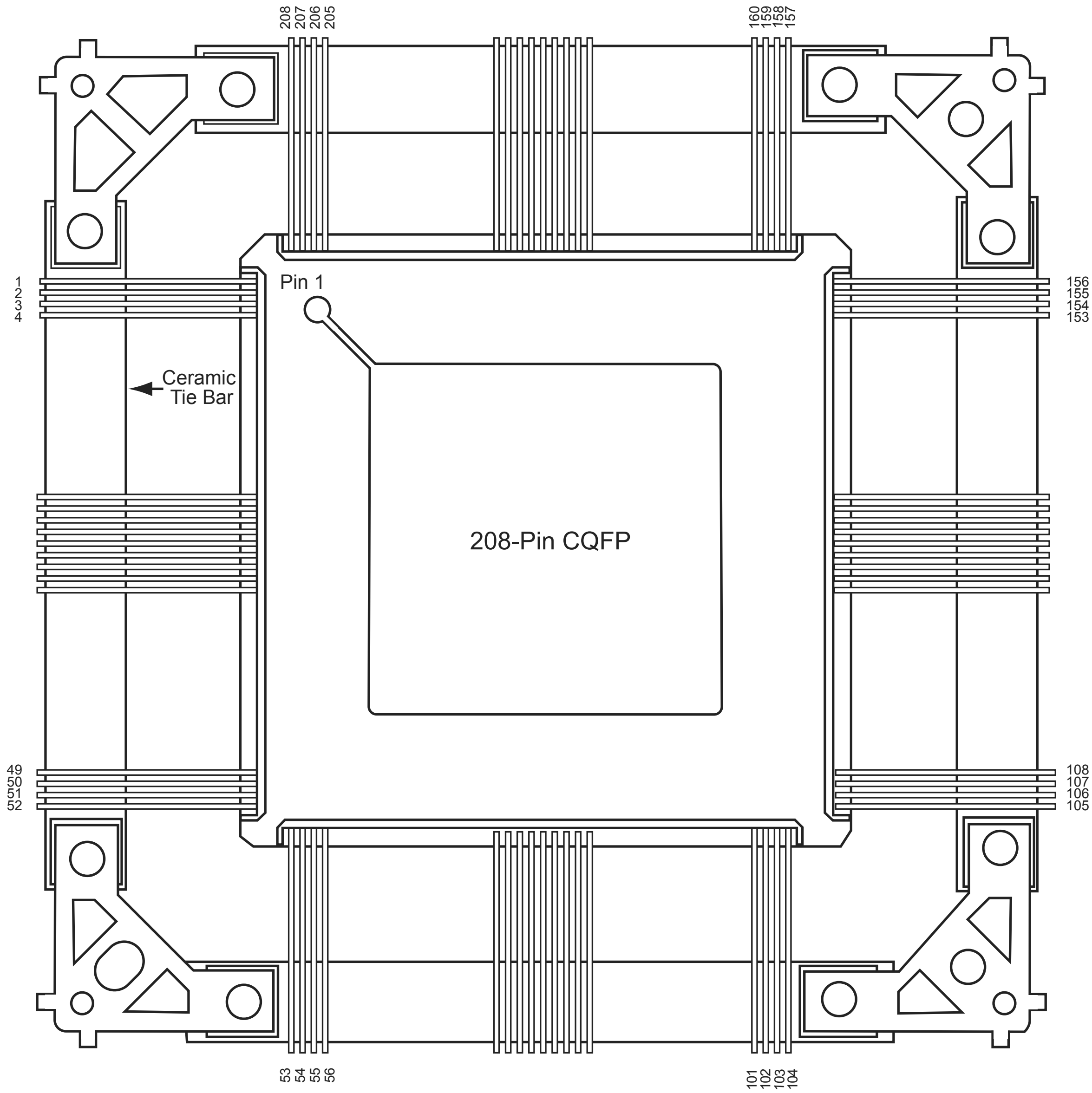
FG1152	
AX2000 Function	Pin Number
GND	A33
GND	A4
GND	A8
GND	AA14
GND	AA15
GND	AA16
GND	AA17
GND	AA18
GND	AA19
GND	AA20
GND	AA21
GND	AB1
GND	AB13
GND	AB22
GND	AB34
GND	AC12
GND	AC23
GND	AC30
GND	AC5
GND	AD11
GND	AD24
GND	AD31
GND	AD4
GND	AE3
GND	AE32
GND	AF2
GND	AF33
GND	AG1
GND	AG27
GND	AG34
GND	AG8
GND	AH28
GND	AH7
GND	AJ29
GND	AJ6

PQ208	
AX250 Function	Pin Number
Bank 0	
IO02NB0F0	197
IO03NB0F0	198
IO03PB0F0	199
IO12NB0F0/HCLKAN	191
IO12PB0F0/HCLKAP	192
IO13NB0F0/HCLKBN	185
IO13PB0F0/HCLKBP	186
Bank 1	
IO14NB1F1/HCLKCN	180
IO14PB1F1/HCLKCP	181
IO15NB1F1/HCLKDN	174
IO15PB1F1/HCLKDP	175
IO16NB1F1	170
IO16PB1F1	171
IO24NB1F1	165
IO24PB1F1	166
IO26NB1F1	161
IO26PB1F1	162
IO27NB1F1	159
IO27PB1F1	160
Bank 2	
IO29NB2F2	151
IO29PB2F2	153
IO30NB2F2	152
IO30PB2F2	154
IO31PB2F2	148
IO32NB2F2	146
IO32PB2F2	147
IO34NB2F2	144
IO34PB2F2	145
IO39NB2F2	139
IO39PB2F2	140
IO40PB2F2	141
IO41NB2F2	137
IO41PB2F2	138
IO43NB2F2	132

PQ208	
AX250 Function	Pin Number
IO43PB2F2	134
IO44NB2F2	131
IO44PB2F2	133
Bank 3	
IO45NB3F3	127
IO45PB3F3	129
IO46NB3F3	126
IO46PB3F3	128
IO48NB3F3	122
IO48PB3F3	123
IO50NB3F3	120
IO50PB3F3	121
IO55NB3F3	116
IO55PB3F3	117
IO57NB3F3	114
IO57PB3F3	115
IO59NB3F3	110
IO59PB3F3	111
IO60NB3F3	108
IO60PB3F3	109
IO61NB3F3	106
IO61PB3F3	107
Bank 4	
IO62NB4F4	100
IO62PB4F4	103
IO63NB4F4	101
IO63PB4F4	102
IO64NB4F4	96
IO64PB4F4	97
IO72NB4F4	91
IO72PB4F4	92
IO74NB4F4/CLKEN	87
IO74PB4F4/CLKEP	88
IO75NB4F4/CLKFN	81
IO75PB4F4/CLKFP	82
Bank 5	
IO76NB5F5/CLKGN	76

PQ208	
AX250 Function	Pin Number
IO76PB5F5/CLKGP	77
IO77NB5F5/CLKHN	70
IO77PB5F5/CLKHP	71
IO78NB5F5	66
IO78PB5F5	67
IO86NB5F5	62
IO87NB5F5	60
IO87PB5F5	61
IO88NB5F5	56
IO88PB5F5	57
IO89NB5F5	54
IO89PB5F5	55
Bank 6	
IO91NB6F6	47
IO91PB6F6	49
IO92NB6F6	48
IO92PB6F6	50
IO93NB6F6	42
IO93PB6F6	43
IO94PB6F6	44
IO96NB6F6	40
IO96PB6F6	41
IO101NB6F6	35
IO101PB6F6	36
IO102PB6F6	37
IO103NB6F6	33
IO103PB6F6	34
IO105NB6F6	28
IO105PB6F6	30
IO106NB6F6	27
IO106PB6F6	29
Bank 7	
IO107NB7F7	23
IO107PB7F7	25
IO108NB7F7	22
IO108PB7F7	24
IO110NB7F7	18

CQ208



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

CQ208	
AX250 Function	Pin Number
IO110PB7F7	19
IO112NB7F7	16
IO112PB7F7	17
IO117NB7F7	12
IO117PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121PB7F7	7
IO122NB7F7	5
IO122PB7F7	6
IO123NB7F7	3
IO123PB7F7	4
Dedicated I/O	
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90
GND	94
GND	99
GND	104
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169
GND	173

CQ208	
AX250 Function	Pin Number
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	14
VCCA	38
VCCA	52
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	156
VCCA	168
VCCA	195
VCCDA	1
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
VCCIB0	193

CQ208	
AX250 Function	Pin Number
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCCPLA	189
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

CQ208	
AX500 Function	Pin Number
Bank 0	
IO03NB0F0	198
IO03PB0F0	199
IO04NB0F0	197
IO19NB0F1/HCLKAN	191
IO19PB0F1/HCLKAP	192
IO20NB0F1/HCLKBN	185
IO20PB0F1/HCLKBP	186
Bank 1	
IO21NB1F2/HCLKCN	180
IO21PB1F2/HCLKCP	181
IO22NB1F2/HCLKDN	174
IO22PB1F2/HCLKDP	175
IO23NB1F2	170
IO23PB1F2	171
IO37NB1F3	165
IO37PB1F3	166
IO39NB1F3	161
IO39PB1F3	162
IO41NB1F3	159
IO41PB1F3	160
Bank 2	
IO43NB2F4	151
IO43PB2F4	153
IO44NB2F4	152
IO44PB2F4	154
IO45PB2F4	148
IO46NB2F4	146
IO46PB2F4	147
IO48NB2F4	144
IO48PB2F4	145
IO57NB2F5	139
IO57PB2F5	140
IO58PB2F5	141
IO59NB2F5	137
IO59PB2F5	138
IO61NB2F5	132

CQ208	
AX500 Function	Pin Number
IO61PB2F5	134
IO62NB2F5	131
IO62PB2F5	133
Bank 3	
IO63NB3F6	127
IO63PB3F6	129
IO64NB3F6	126
IO64PB3F6	128
IO66NB3F6	122
IO66PB3F6	123
IO68NB3F6	120
IO68PB3F6	121
IO77NB3F7	116
IO77PB3F7	117
IO79NB3F7	114
IO79PB3F7	115
IO81NB3F7	110
IO81PB3F7	111
IO82NB3F7	108
IO82PB3F7	109
IO83NB3F7	106
IO83PB3F7	107
Bank 4	
IO84PB4F8	103
IO85NB4F8	100
IO86NB4F8	101
IO86PB4F8	102
IO87NB4F8	96
IO87PB4F8	97
IO101NB4F9	91
IO101PB4F9	92
IO103NB4F9/CLKEN	87
IO103PB4F9/CLKEP	88
IO104NB4F9/CLKFN	81
IO104PB4F9/CLKFP	82
Bank 5	
IO105NB5F10/CLKGN	76

CQ208	
AX500 Function	Pin Number
IO105PB5F10/CLKGP	77
IO106NB5F10/CLKHN	70
IO106PB5F10/CLKHP	71
IO107NB5F10	66
IO107PB5F10	67
IO119NB5F11	62
IO121NB5F11	60
IO121PB5F11	61
IO123NB5F11	56
IO123PB5F11	57
IO125NB5F11	54
IO125PB5F11	55
Bank 6	
IO127NB6F12	47
IO127PB6F12	49
IO128NB6F12	48
IO128PB6F12	50
IO129NB6F12	42
IO129PB6F12	43
IO130PB6F12	44
IO132NB6F12	40
IO132PB6F12	41
IO141NB6F13	35
IO141PB6F13	36
IO142PB6F13	37
IO143NB6F13	33
IO143PB6F13	34
IO145NB6F13	28
IO145PB6F13	30
IO146NB6F13	27
IO146PB6F13	29
Bank 7	
IO147NB7F14	23
IO147PB7F14	25
IO148NB7F14	22
IO148PB7F14	24
IO150NB7F14	18

CQ352	
AX500 Function	**Pin Number**
Bank 0	
IO00PB0F0	343
IO03NB0F0	341
IO03PB0F0	342
IO05NB0F0	337
IO05PB0F0	338
IO07NB0F0	335
IO07PB0F0	336
IO09NB0F0	331
IO09PB0F0	332
IO15NB0F1	325
IO15PB0F1	326
IO17NB0F1	323
IO17PB0F1	324
IO19NB0F1/HCLKAN	319
IO19PB0F1/HCLKAP	320
IO20NB0F1/HCLKBN	313
IO20PB0F1/HCLKBP	314
Bank 1	
IO21NB1F2/HCLKCN	305
IO21PB1F2/HCLKCP	306
IO22NB1F2/HCLKDN	299
IO22PB1F2/HCLKDP	300
IO23NB1F2	289
IO23PB1F2	290
IO24NB1F2	295
IO24PB1F2	296
IO25NB1F2	287
IO25PB1F2	288
IO27NB1F2	283
IO27PB1F2	284
IO29NB1F2	281
IO29PB1F2	282
IO31NB1F2	277
IO31PB1F2	278

CQ352	
AX500 Function	**Pin Number**
IO35NB1F3	275
IO35PB1F3	276
IO37NB1F3	271
IO37PB1F3	272
IO41NB1F3	269
IO41PB1F3	270
Bank 2	
IO43NB2F4	261
IO43PB2F4	262
IO45NB2F4	259
IO45PB2F4	260
IO47NB2F4	255
IO47PB2F4	256
IO49NB2F4	253
IO49PB2F4	254
IO50NB2F4	247
IO50PB2F4	248
IO51NB2F4	249
IO51PB2F4	250
IO53NB2F5	243
IO53PB2F5	244
IO54NB2F5	241
IO54PB2F5	242
IO55NB2F5	237
IO55PB2F5	238
IO57NB2F5	235
IO57PB2F5	236
IO58NB2F5	231
IO58PB2F5	232
IO59NB2F5	229
IO59PB2F5	230
IO61NB2F5	225
IO61PB2F5	226
IO62NB2F5	223
IO62PB2F5	224

CQ352	
AX500 Function	**Pin Number**
Bank 3	
IO63NB3F6	217
IO63PB3F6	218
IO64NB3F6	219
IO64PB3F6	220
IO65NB3F6	213
IO65PB3F6	214
IO67NB3F6	207
IO67PB3F6	208
IO68NB3F6	211
IO68PB3F6	212
IO69NB3F6	205
IO69PB3F6	206
IO71NB3F6	201
IO71PB3F6	202
IO73NB3F6	199
IO73PB3F6	200
IO75NB3F7	193
IO75PB3F7	194
IO76NB3F7	195
IO76PB3F7	196
IO77NB3F7	189
IO77PB3F7	190
IO79NB3F7	187
IO79PB3F7	188
IO80NB3F7	183
IO80PB3F7	184
IO81NB3F7	181
IO81PB3F7	182
IO83NB3F7	179
IO83PB3F7	180
Bank 4	
IO85NB4F8	172
IO85PB4F8	173
IO87NB4F8	170

CG624	
AX2000 Function	Pin Number
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	T21
GND	T23
GND	T3
GND	T5
GND	V1
GND	V25
GND	V5
PRA	F13
PRB	A13
PRC	AB12
PRD	AE13
TCK	F5

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
TDI	C5
TDO	F6
TMS	D6
TRST	E6
VCCA	AB20
VCCA	F22
VCCA	F4
VCCA	J17
VCCA	J9
VCCA	K10
VCCA	K11
VCCA	K15
VCCA	K16
VCCA	L10
VCCA	L16
VCCA	R10
VCCA	R16
VCCA	T10
VCCA	T11
VCCA	T15
VCCA	T16
VCCA	U17
VCCA	U9
VCCA	Y4
VCCDA	A12
VCCDA	A14
VCCDA	AA13
VCCDA	AA15
VCCDA	AA20
VCCDA	AA7
VCCDA	AB13
VCCDA	AC11

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
VCCDA	AD11
VCCDA	AD4
VCCDA	AE12
VCCDA	AE17
VCCDA	B15
VCCDA	C15
VCCDA	C6
VCCDA	D13
VCCDA	E13
VCCDA	E19
VCCDA	F21
VCCDA	G10
VCCDA	G5
VCCDA	N21
VCCDA	N5
VCCDA	W21
VCCIB0	A3
VCCIB0	B3
VCCIB0	C4
VCCIB0	D5
VCCIB0	J10
VCCIB0	J11
VCCIB0	K12
VCCIB1	A23
VCCIB1	B23
VCCIB1	C22
VCCIB1	D21
VCCIB1	J15
VCCIB1	J16
VCCIB1	K14
VCCIB2	C24
VCCIB2	C25

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

Revision	Changes	Page
Revision 3 (continued)	The timing characteristics tables from pages 2-26 to 2-60 were updated.	2-26 to 2-60
	The "Global Resources" section was updated.	2-66
	The timing characteristics tables from pages 2-102 to 2-103 were updated.	2-102 to 2-103
	The "PQ208", "FG256", and "FG324" tables are new.	3-9,3-16, 3-84

Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in the "Axcelerator Family Device Status" table on page iii, is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

Production

This version contains information that is considered to be final.

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